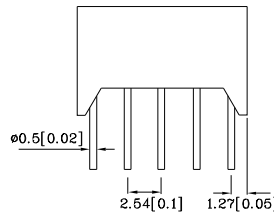
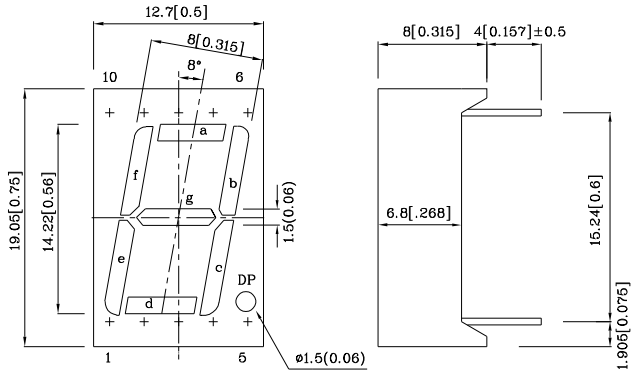
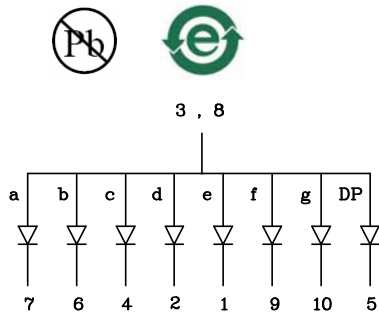


PRELIMINARY SPEC

Features

- 0.56 INCH DIGIT HEIGHT.
- LOW CURRENT OPERATION.
- EXCELLENT CHARACTER APPEARANCE.
- EASY MOUNTING ON P.C. BOARDS OR SOCKETS.
- I.C. COMPATIBLE.
- MECHANICALLY RUGGED.
- STANDARD : GRAY FACE, WHITE SEGMENT.
- RoHS COMPLIANT.



ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

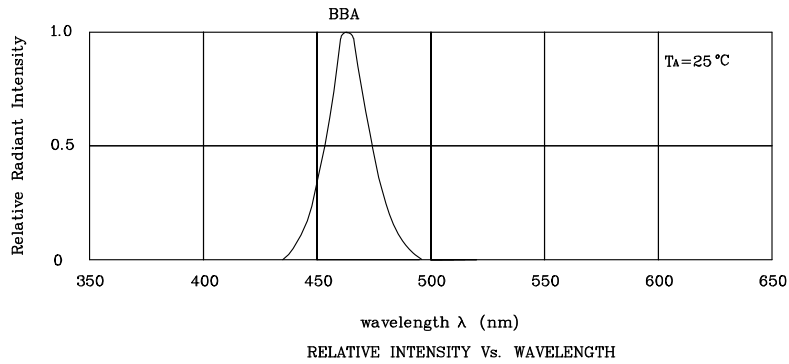
Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is $\pm 0.25(0.01)$ unless otherwise noted.
3. Specifications are subject to change without notice.

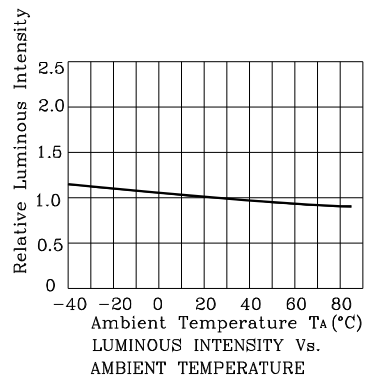
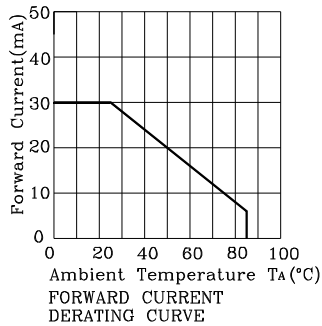
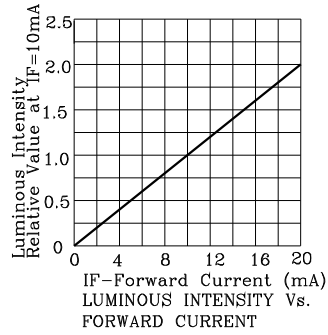
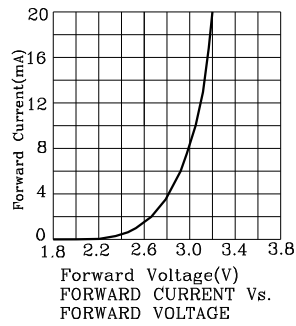
Absolute Maximum Ratings (TA=25°C)		BBA (InGaN)	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	30	mA
Forward Current (Peak) 1/10 Duty Cycle 0.1ms Pulse Width	i _{FS}	100	mA
Power Dissipation	P _T	120	mW
Operating Temperature	T _A	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	
Electrostatic Discharge Threshold (HBM)		1000	V
Lead Solder Temperature [2mm Below Package Base]	260°C For 3~5 Seconds		

Operating Characteristics (TA=25°C)		BBA (InGaN)	Unit
Forward Voltage (Typ.) (I _F =10mA)	V _F	3.05	V
Forward Voltage (Max.) (I _F =10mA)	V _F	4.0	V
Reverse Current (Max.) (V _R =5V)	I _R	10	uA
Wavelength Of Peak Emis- sion (Typ.) (I _F =10mA)	λ _P	468	nm
Wavelength Of Dominant Emission (Typ.) (I _F =10mA)	λ _D	470	nm
Spectral Line Full Width At Half-Maximum (Typ.) (I _F =10mA)	Δλ	21	nm
Capacitance (Typ.) (V _F =0V, f=1MHz)	C	100	pF

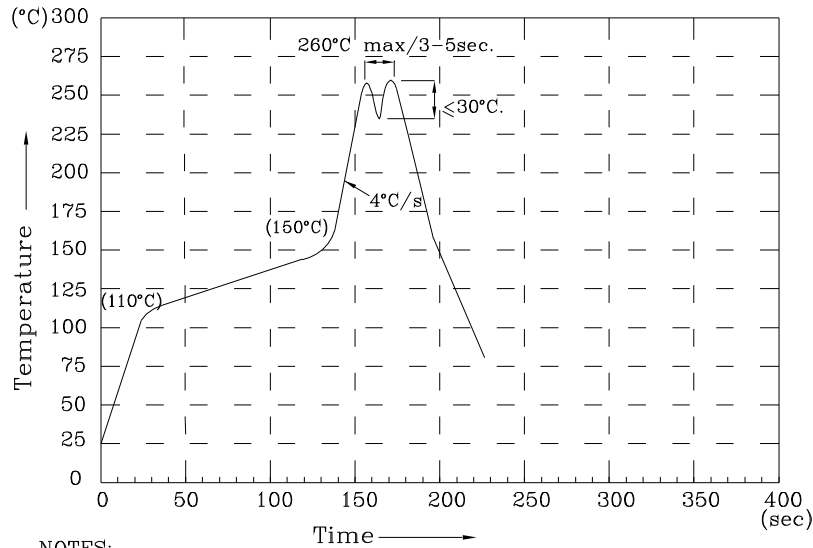
Part Number	Emitting Color	Emitting Material	Luminous Intensity (I _F =10mA) ucd		Wavelength nm λ _P	Description
			min.	typ.		
XDBBA14A	Blue	InGaN	1900	10290	468	Common Anode, Rt. Hand Decimal
Published Date : JAN 04, 2008		Drawing No : XDSA8936	V4	Checked : Shin Chi	P.1/4	



❖ **BBA**



Wave Soldering Profile For Lead-free Through-hole LED.



NOTES:

1. Recommend the wave temperature 245°C~260°C. The maximum soldering temperature should be less than 260°C.
2. Do not apply stress on epoxy resins when temperature is over 85 degree°C.
3. The soldering profile apply to the lead free soldering (Sn/Cu/Ag alloy).
4. No more than once.

Remarks:

If special sorting is required (e.g. binning based on forward voltage, luminous intensity / luminous flux, or wavelength),

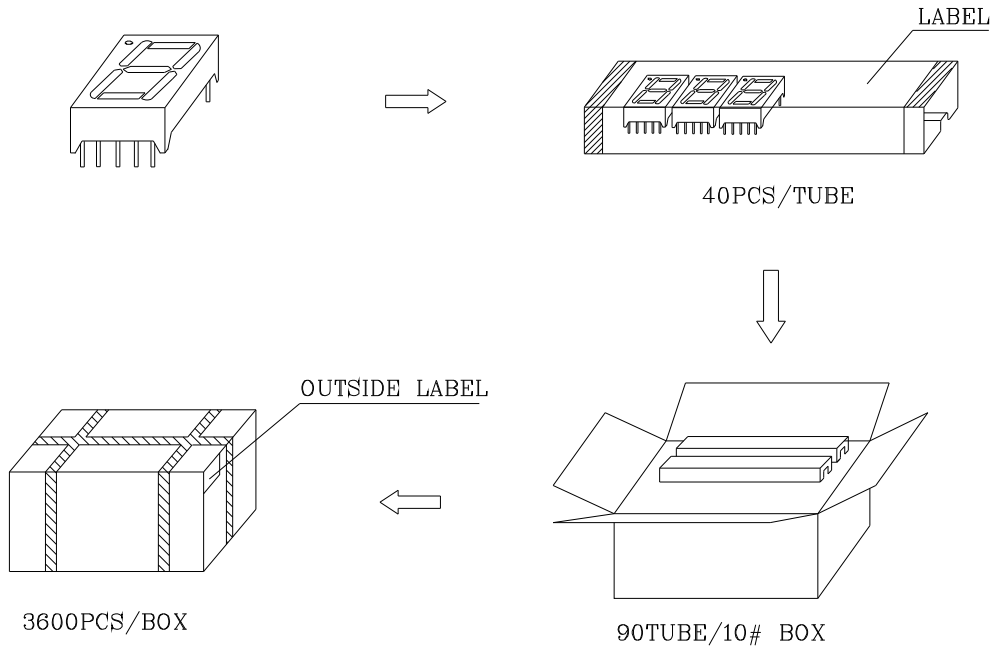
the typical accuracy of the sorting process is as follows:

1. Wavelength: +/-1nm
2. Luminous Intensity / Luminous Flux: +/-15%
3. Forward Voltage: +/-0.1V

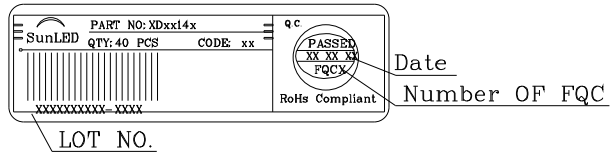
Note: Accuracy may depend on the sorting parameters.

PACKING & LABEL SPECIFICATIONS

XDBBA14A



Inside LABEL Paste On The IC-tube



Outside LABEL Paste On The Box

